

You are invited!

TRI will showcase the latest 3D SPI and 3D AOI solutions for SEMICON packaging applications at SEMICON Taiwan 2017. Discover the highest precision inspection at TRI booth #908!

TR7500QE · 3D AOI



- Multi-angle 2D + 3D Coverage
- 4-way DLP Fringe Projection
- 3D Solder Joint Inspection
- Fast CoaXPress Imaging

TR7007Q · 3D SPI



- Multi-angle 2D + 3D Coverage
- 2015 Global Tech Award Winner
- Market Leading Inspection Speed and Precision
- Fast CoaXPress Imaging